CHIPQUIK[®]

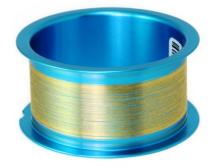
Datasheet revision 1.3

www.chipquik.com

Gold Bonding Wire (Au100) Gold 25um (1.0mil)

Product Highlights

High Purity Gold > 99.99% (4N). Designed specifically for wire bonding. Gold bonding wire is used to connect electrical components in many industries, including electronics, aerospace and medicine. Gold bonding wire has excellent electrical conductivity, stability and resistance to corrosion. It is an important material in semiconductor and electronic device manufacturing. It is commonly used for wire bonding to electrically connect microchip semiconductor dies to the terminals of a chip package or directly to a substrate. Commonly used by integrated circuit (IC) packaging shops, research labs and advanced manufacturing facilities.



CQB-AU100-25um

Specifications				
Use:	Gold Bonding Wire			
Alloy:	Au100			
Tensile Strength:	9-15 gf			
Elongation (%):	10-16			
Melting Point:	1,064°C (1,947°F)			
Packaging:	Spool			
Diameter:	25µm (1.0 mil)			
Length:	100m (328 feet)			
Shelf Life:	> 12 months			
Purity:	4N (>99.99%)			
Wire Weight:	950 mg			
Storage and Handling	Store in a dry non-corrosive environment.			
Transportation	This product has no shipping restrictions.			

Test Results		
Test J-STD-004 or other	Test Requirement	Result
requirements as stated		
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Compliant

Conforms to the following Industry Standards: J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): RoHS 3 Directive (EU) 2015/863:

Yes Yes

Chip Quik Gold Bonding Wire (Au100) Orderable Part Numbers

Part Number	Gold (Au) Purity	Tensile Strength	Elongation (%)	Diameter	Length	Photo
CQB-AU100-20um	4N (>99.99%)	7-11 gf	8-14	20µm (0.8 mil)	100m (328 feet)	
CQB-AU100-23um	4N (>99.99%)	8-14 gf	10-16	23µm (0.9 mil)	100m (328 feet)	
CQB-AU100-25um	4N (>99.99%)	9-15 gf	10-16	25µm (1.0 mil)	100m (328 feet)	